

Datacon 2200 EVO Dispense Pick and Place

Asset ID: 14562

Configuration:

Datacon 2200 EVO Dispense Pick and Place

- Die Handling System
- Upgrade Heated Bond Head
- Single Head Machine
- Epoxy and flux application system
- DC6408 Slide flux
- Substrate Transport System
- Input/Output System
- Wafer Table w/o stretcher
- Wafer lift including wafer changer
- Gel-Pak Holder 2" for auto cahnge (8")
- Flip Chip Station
- Auto tool changer unit, 7 slot
- Single-Chip ejector unit
- Eject tool base
- Needle Kit
- Dispenser high performance D-Style Pump
- Calibration Tool Kit
- SECS/GEM Capability including wafer mapping and wafer scanner
- ID Integrated Dispenser
- ALPS EL Host Computer
- Die Handling System
- Epoxy and Flux Application System

2011 Vintage

Photos on Following Pages

To our knowledge, the information contained in this data sheet is accurate, but it may contain errors and we do not warrant the completeness or accuracy of this data.

Interested parties may contact Bridge Tronic Global for additional information at +1 949.396.1395 or sales@bridgetronic.com

Visit our website at: www.bridgetronic.com



QUICK LEAD TIMES



QUALITY









QUICK LEAD TIMES



QUALITY EQUIPMENT









QUICK LEAD TIMES













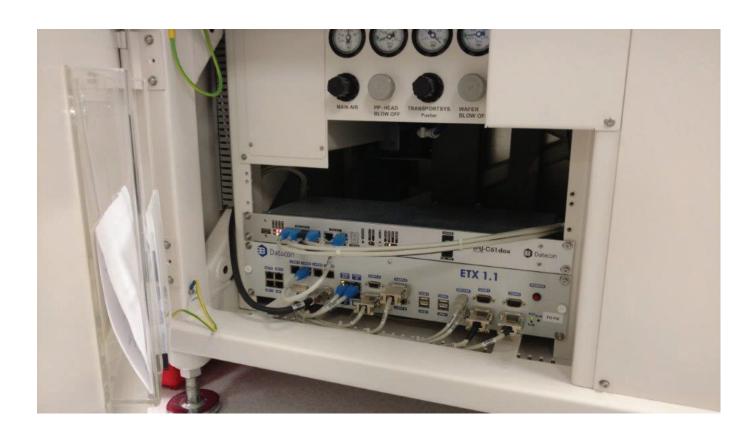
QUICK LEAD TIMES



QUALITY









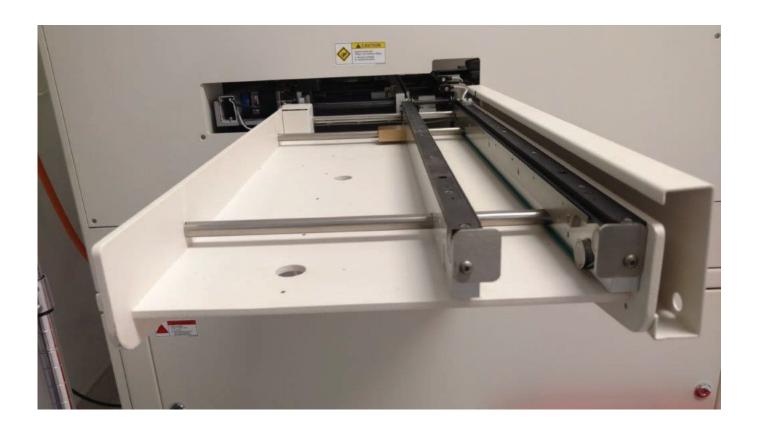
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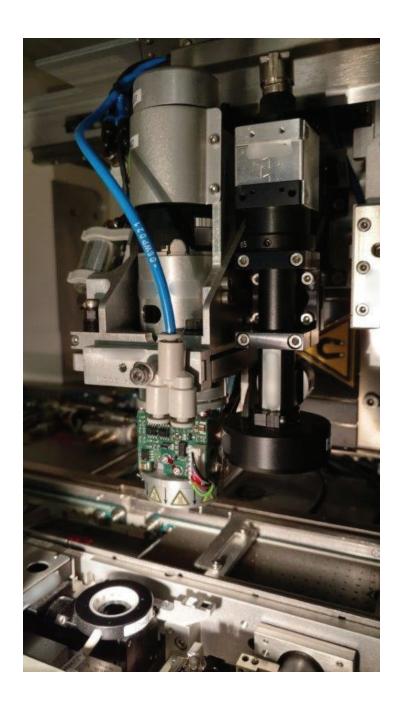
QUICK LEAD TIMES



QUALITY EQUIPMENT









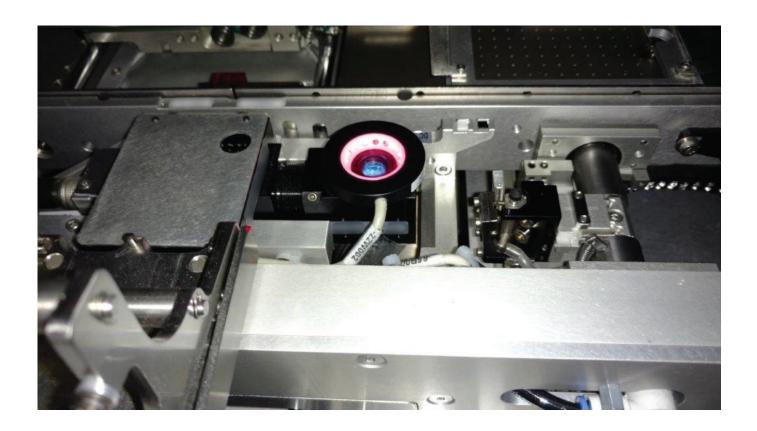
QUICK LEAD TIMES



QUALITY







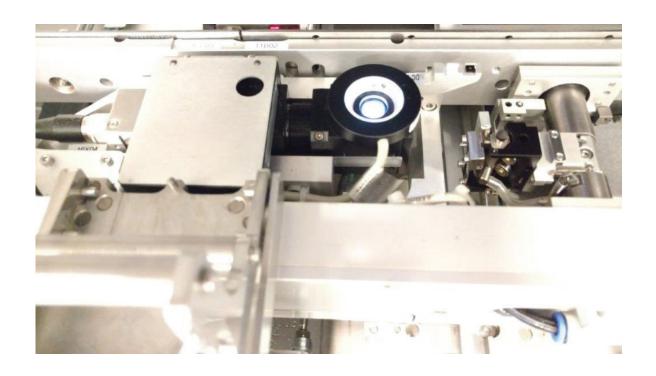


























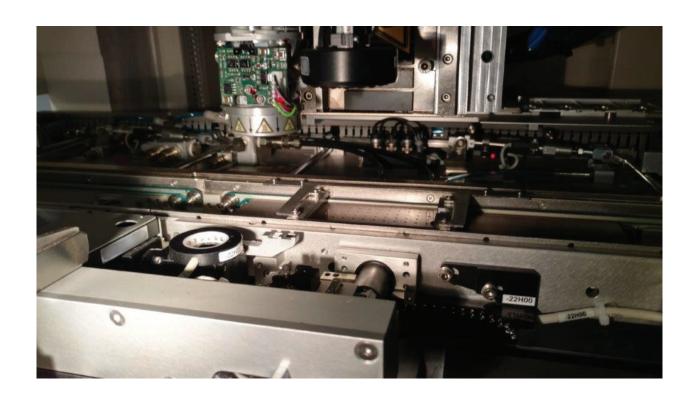














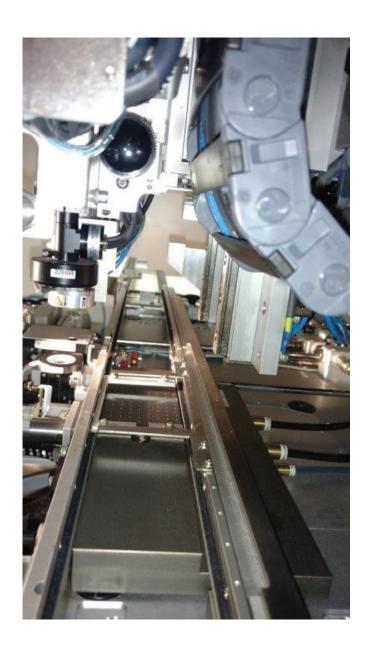












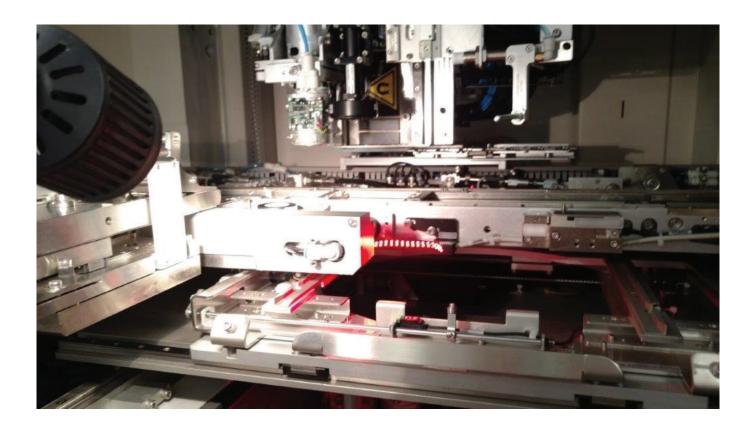














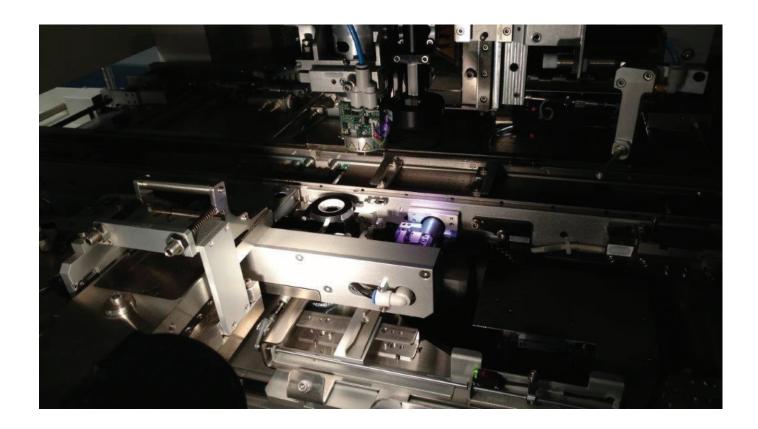














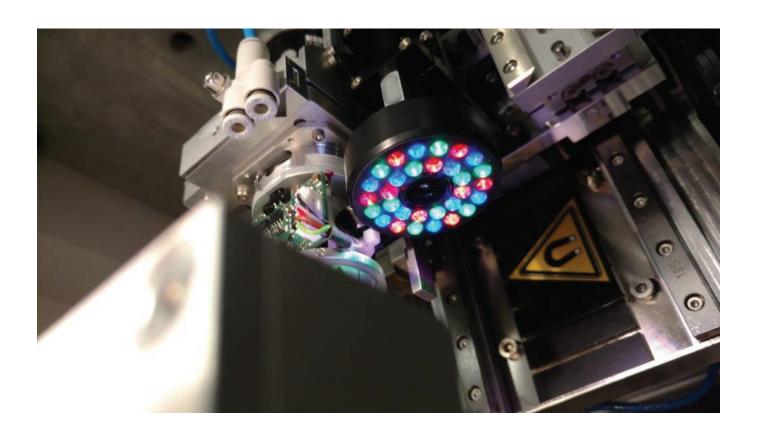
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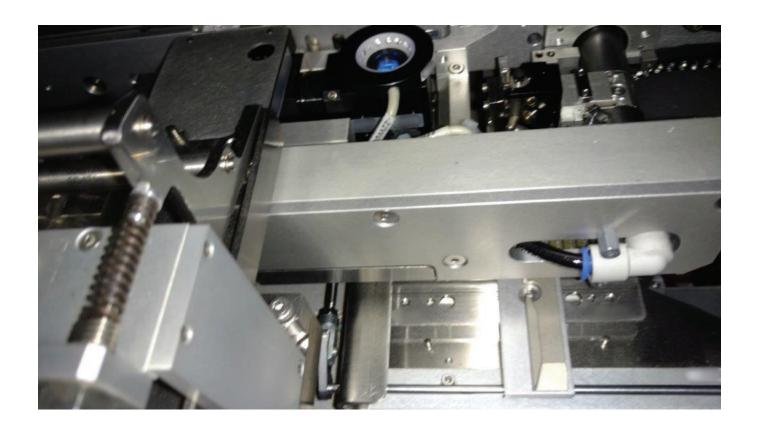














QUICK LEAD TIME:



QUALITY EQUIPMENT









QUICK LEAD TIMES













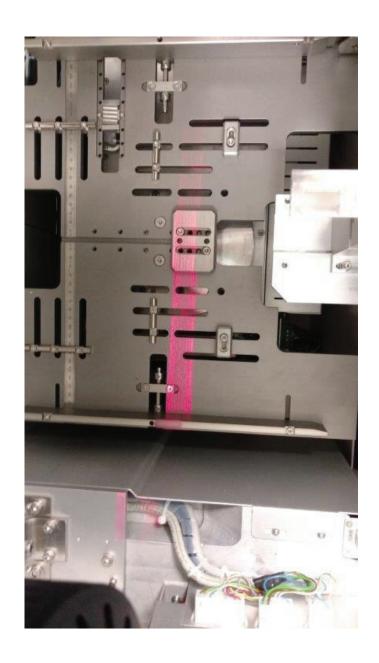














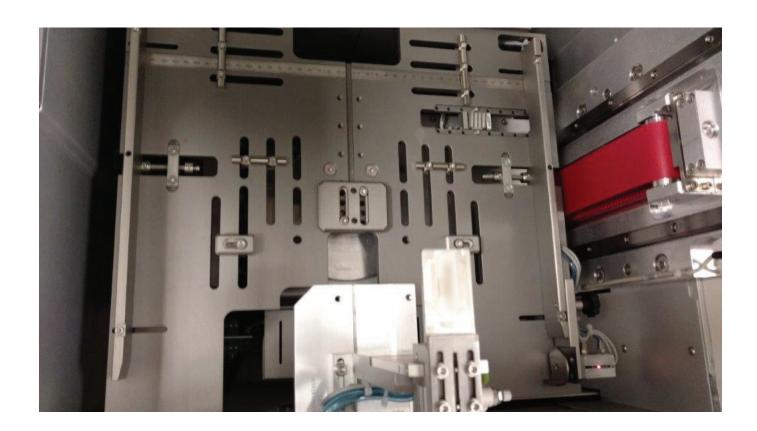
QUICK LEAD TIME



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